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This index covers all items - papers, correspondence, reviews, etc. that appeared in this periodical during 1992, and items from previous years that were commented upon or corrected in 1992.

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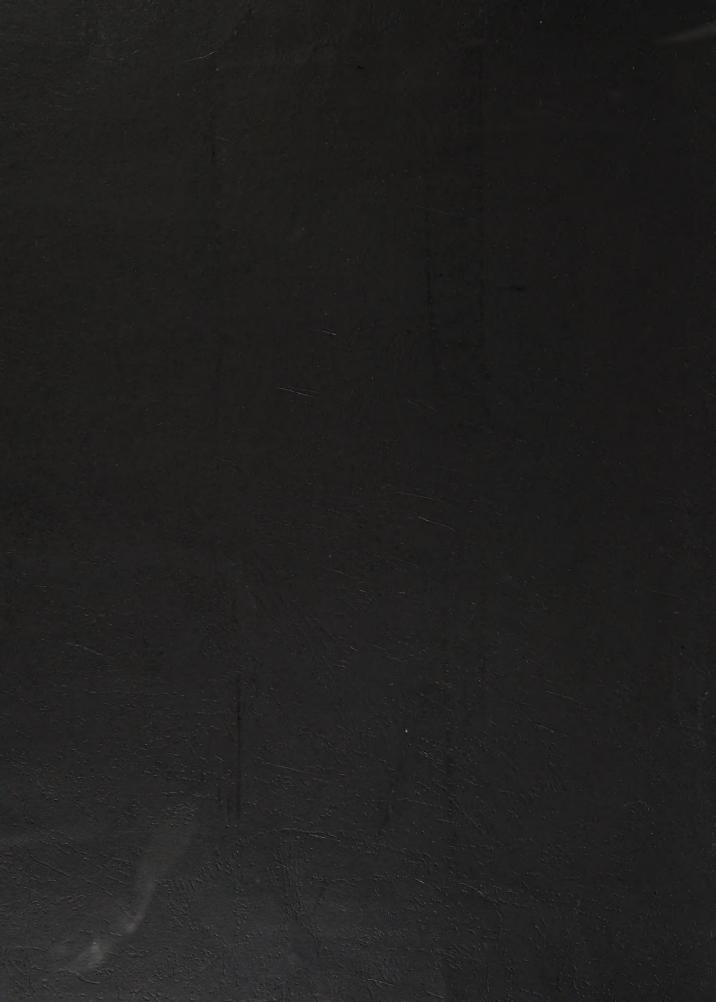
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Integrated circuit testing; cf. Integrated circuit reliability

Integrated circuit thermal factors

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Interconnections, integrated-circuits; cf. Hybrid integrated-circuit interconnections

Interferometry; cf. Infrared interferometry

Ion implantation; cf. Integrated circuit ion implantation

Ion radiation effects; cf. Integrated circuit fabrication; Integrated circuit

IEEE Transactions on Semiconductor Manufacturing; cf. Awards

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